05 May 2004

L Number	Hits	Search Text	DB	Time stamp
6	2	6001229.pn.	USPAT;	2004/05/05
		•	U5-PGPUB;	09:47
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
12	210	204/450-470,600-621.ccls. and	USPAT;	2004/05/05
		(polytetrafluoroethylene or PTFE)	US-PGPUB;	09:48
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
13	176	204/600-621.ccls. and (polytetrafluoroethylene or	USPAT;	2004/05/05
		PTFE)	US-PGPUB;	09:51
		, .	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
14	4	6321791.pn. 6167910.pn.	USPAT;	2004/05/05
••	· ·	0021, 71, 11, 11, 11, 11, 11, 11, 11, 11, 1	US-PGPUB;	09:57
			EPO; JPO;	05.07
			DERWENT;	
			IBM_TDB	
15	418	204/600,601,606.ccls. and array and (plate or chip or	USPAT;	2004/05/05
13	710	microchip or microfluidic)	US-PGPUB;	10:15
		microcrup or microfididic)	EPO; JPO;	10.13
			DERWENT;	
			IBM_TDB	
16	23	204/\$.ccls. and aclara.asn.	USPAT;	2004/05/05
10	23	2047 \$.ccis. and aciara.asn.	US-PGPUB;	10:15
			1	10.15
			EPO; JPO; DERWENT;	
	•		1	
	20/8		IBM_TDB	2004/04/27
-	2068	sample.ti. and plate.ti.	USPAT;	2004/04/27
			US-PGPUB;	09:26
			EPO; JPO;	
			DERWENT;	
	4.44	normale at end please at end mail at	IBM_TDB	2002/00/22
-	141	sample.ti. and plate.ti. and well.ti.	USPAT;	2003/09/23
		·	US-PGPUB;	13:44
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			DERWENT;	
	0.5	110 47070E0 # DTD 00 110 4007/04 # DTD 00	IBM_TDB	2004/04/22
-	25	US-4797259-\$.DID. OR US-4927604-\$.DID. OR	USPAT	2004/04/28
		US-5580747-\$.DID. OR US-5605662-\$.DID. OR		10:20
		US-5632957-\$.DID. OR US-5849486-\$.DID. OR		
		US-5129208-\$.DID. OR US-6017696-\$.DID. OR	,	
		US-6051380-\$.DID. OR US-5376252-\$.DID. OR		
		US-5580747-\$.DID. OR US-5858188-\$.DID. OR		
		US-5904824-\$.DID. OR US-5932315-\$.DID. OR		
		US-5942443-\$.DID. OR US-5948227-\$.DID. OR		
		US-5957579-\$.DID. OR US-5958202-\$.DID. OR		
		US-5965001-\$.DID. OR US-5976336-\$.DID. OR		
		US-6046056-\$.DID. OR US-6068752-\$.DID. OR		
		US-6074827-\$.DID. OR US-6093296-\$.DID. OR		
		US-6103199-\$.DID. OR US-6103537-\$.DID.		

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-	2	jp-62247247-\$.did.	USPAT;	2004/04/28
		(US-PGPUB;	10:48
		•	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	1	1987-344377.NRAN.	DERWENT	2004/04/28
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-	1	1997wo-us13525.ap,prai.	USPAT;	2004/04/28
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			IBM_TDB	
-	1	1998-193779.NRAN.	DERWENT	2004/04/28
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-	2	6129828.pn.	USPAT;	2004/04/28
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			DERWENT;	
			IBM_TDB	
_	1	2000wo-us05320.ap,prai.	USPAT;	2004/04/28
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_	2	6585939.pn.	USPAT;	2004/04/28
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_	1	1998wo-us21869.ap,prai.	USPAT;	2004/04/28
		1990wo use1009.up,prai.	US-PGPUB;	10:51
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			DERWENT;	
			IBM_TDB	
	4	6129828.pn. 6585939.pn.	USPAT;	2004/04/28
		012/020.pm. 0000/0/.pm.	US-PGPUB;	10:54
		,	EPO; JPO;	10.04
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	1		IBM_TDB	
	2202	204/600,601,605,606,614,627,630-640.ccls.	USPAT;	2004/04/28
-	2202	20-7,000,001,000,000,01-7,027,000-0-10.0015.	US-PGPUB;	10:59
			EPO; JPO;	10.57
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	2	6056850 nn	USPAT;	2004/04/28
-	"	6056859.pn.	US-PGPUB;	11:00
			EPO; JPO;	11.00
			DERWENT;	
	40	2047/27 - 14	IBM_TDB	2004/04/28
-	218	204/627.ccls.	USPAT;	2004/04/28
			US-PGPUB;	13:58
			EPO; JPO;	
			DERWENT;	
	L		IBM_TDB	

		T	,	
-	878	204/627-640.ccls.	USPAT;	2004/04/30
			US-PGPUB;	10:11
			EPO; JPO;	
			DERWENT;	-
			IBM_TDB	
	23	204/627 640 and only and fluid \$4 an initial and the		2004/04/20
-	23	204/627-640.ccls. and (microfluid\$4 or microconduit	USPAT;	2004/04/28
		or chip or tas! wafer)	US-PGPUB;	15:07
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			DERWENT;	
			IBM_TDB	
-	7	6103537.URPN.	USPAT	2004/04/28
				14:22
	30	("3935074" "3984533" "3996345" "4098876"	USPAT	2004/04/28
-	30		USPAT	1
		"4141687" "4275149" "4318980" "4529561"		14:32
		"4619904" "4628037" "4634681" "4652533"		
		"4695392" "4772550" "5089390" "5185243"		
		"5472584" "5527710" "5532138" "5536382"		
		"5541113" "5571680" "5591581" "5610017"		
		"5630924" "5685965" "5810985" "5833826"		
		"5853668" "5898005").PN.		
	2	204/600,601,605,606,614,627,630-640.ccls. and	USPAT;	2004/04/28
-	-			l i
		(capture adj matrix)	US-PGPUB;	15:07
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	325	204/600,601,605,606,614,627,630-640.ccls. and	USPAT;	2004/04/28
		(binding)	US-PGPUB;	15:07
		(biliding)	EPO; JPO;	15.07
1			DERWENT;	
			IBM_TDB	
-	168	(204/600,601,605,606,614,627,630-640.ccls. and	USPAT;	2004/04/28
		(binding)) and (microfluid\$4 or microconduit or chip	US-PGPUB;	15:08
		or tas! wafer)	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	1	1998-193779.NRAN.	DERWENT	2004/04/29
				15:01
_	280	204/627-640.ccls. and plate	USPAT;	2004/04/29
-	200	LOT/OL/-OTO.CCIS. and plate	· ·	1
[US-PGPUB;	15:25
	1		EPO; JPO;	
		·	DERWENT;	
			IBW_TDB	
-	95	(204/627-640.ccls. and plate) and (quantit\$7 or	USPAT;	2004/04/29
		quantif\$7)	U5-PGPUB;	15:25
	[EPO; JPO;	
			DERWENT;	
		2001/40 1164/025	IBM_TDB	2004/04/20
-	1	2001WO-US46035.ap,prai.	USPAT;	2004/04/30
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			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	1	2002-566566.NRAN.	DERWENT	2004/04/30
	•			09:54
	L			U 7 1 3 T

-	114	204/627-640.ccls. and gradient	USPAT;	2004/04/30
			US-PGPUB;	10:11
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			DERWENT;	
			IBM_TDB	
_	1	jp-11311616-\$.did.	USPAT;	2004/05/04
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			DERWENT;	
			IBW_TDB	
_	1	2000-048669.NRAN.	DERWENT	2004/05/04
				14:00